



This international symposium continues to focus on recent developments and future directions in Quality and Reliability Management of materials, devices and circuits for micro-, nano-, and optoelectronics. It provides a European forum for developing all aspects of reliability management and innovative analysis techniques for present and future electronic applications.



ESREF 2025 will be held in Bordeaux. Bordeaux is part of the UNESCO World Heritage List, and classified as "City of Art and History".

ESREF 2025 will be organized by IMS laboratory, University of Bordeaux in collaboration with LAAS-CNRS, University of Toulouse, CNES (french space agency) and ADERA.

Hosting ESREF 2025 is a great opportunity since reliability in these particular applications is a very hot topic with strong challenges such as zero ppm failure and harsh environments. For this 36th edition, in addition to the core topics of the conference, we would like to involve the major actors of aeronautics, space and embedded systems industry to provide specific topics such as radiation hardening, very long-term reliability, high/low temperature challenges, obsolescence and counterfeit issues, wide band gap power devices for the more electric aircraft and other embedded system applications.

A large place will be given to exhibitors. The Symposium will feature the latest in service providers, equipment manufacturer and suppliers in this fields.

We are looking forward to welcoming you for a memorable experience!

SUBMISSION GUIDELINES

The deadline for the submission of summaries is **March 10, 2025**. A 4 pages abstract should clearly present the importance of the work and specific results. Authors are requested to upload an electronic file (in PDF) of the summary at <https://esref2025.sciencesconf.org/>

DEADLINES

10 March 2025	Submission of a 4 pages abstract
9 May 2025	Notification of acceptance for the conference
10 June 2025	Submission of the 4 pages conference paper for proceedings

Elsevier Ltd will publish ESREF 2025 selection of extended papers in a special issue of the Microelectronics Reliability journal.

SCOPE OF PAPERS

Quality and Reliability assessment techniques and methods for Devices and Systems	Packaging and Assembly Reliability and Failure Analysis
Semiconductor Failure Mechanisms & Reliability for Si technologies & Nanoelectronics	Power Devices and Microelectronic System: Reliability and Failure Analysis
Progress in Failure Analysis: Defect Detection and Analysis	Photonics Reliability
Reliability of Microwave devices and circuits	MEMS and sensors Reliability
	Extreme environments and Radiation

ORGANIZING COMMITTEE

Conference Chair :		Industrial Exhibition:	
F. MARC	IMS, University of Bordeaux (France)	G. BASCOUL	CNES (France)
Technical Program Chairs:		C. DUFFOUR	ADERA Congrès (France)
G. BASCOUL	CNES (France)	Organisation Secretariat:	
A. GRACIA	IMS, University of Bordeaux (France)	C. DUFFOUR	ADERA Congrès (France)
N. LABAT	IMS, University of Bordeaux (France)		
N. NOLHIER	LAAS-CNRS (France)		
L. THEOLIER	IMS, University of Bordeaux (France)		

CONTACT

Email : esref2025@sciencconf.org

WebSite : <https://esref2025.sciencconf.org/>